

RELIABILITY MONITOR

DS1100Z-25 JUL '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1100	A3	0323	DJ330003ACC	8	SOIC	150x1.4	NSEB
PROCESS		D6W-1P2M,HPVt,E2,TCZ PBL:GOI		Passivation w/Nov TEOS Oxide-Nitride			

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse: °C
 Vuse: Volts

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31899	HIGH TEMP OP LIFE	125C, 5.5 VOLTS	80	500	HRS	0
		125C, 5.5 VOLTS	80	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 12	DEVICE HRS: 7.55E+07
31896	ULTRASOUND	J-STD-020	4	1	DYS	0
		TOTAL:				0
31897	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	241	24	HRS	
		85 C/85% R.H.	241	168	HRS	
		235C	241	3	PASS	0
		TOTAL:				0
31898	PRECONDITION U/S	J-STD-020	4	1	DYS	0
		TOTAL:				0
31900	TEMP CYCLE	-55C TO 125C	40	500	CYS	0
			40	1000	CYS	0
		TOTAL:				0
31901	BIASED MOISTURE	85/85, 5.5 VOLTS	77	500	HRS	0
			77	1000	HRS	0
		TOTAL:				0

PROJECT NO: 27782

RELIABILITY MONITOR

DS1100Z-25 JUL '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1100	A3	0323	DJ330003ACC	8	SOIC	150x1.4	NSEB
PROCESS		D6W-1P2M,HPVt,E2,TCZ PBL:GOI		Passivation w/Nov TEOS Oxide-Nitride			

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	<input type="text" value="60%"/>	Tuse:	<input type="text" value="25 °C"/>
Ea:	<input type="text" value="0.7"/>	Vuse:	<input type="text" value="5.5 Volts"/>
β:	<input type="text" value="0"/>		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31902	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	0
TOTAL:						0

RELIABILITY MONITOR

DS1232L JUL '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1232	C2-L	0327	DK343027AAB	8	SOIC	150x1.4	ATP (Amkor, PI)
PROCESS 1P, 1M, 0.8um, PdplDiode, Low Vts , Passivation w/Nov TEOS Oxide-Nitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse:
 Vuse:

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31906	HIGH TEMP OP LIFE	125C, 5.5 VOLTS	80	500	HRS	0
		125C, 5.5 VOLTS	80	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 12	DEVICE HRS: 7.55E+07
31903	ULTRASOUND	J-STD-020	4	1	DYS	0
		TOTAL:				0
31904	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	241	24	HRS	
		85 C/85% R.H.	241	168	HRS	
		235C	241	3	PASS	0
		TOTAL:				0
31905	PRECONDITION U/S	J-STD-020	4	7	DYS	0
		TOTAL:				0
31907	TEMP CYCLE	-55C TO 125C	40	500	CYS	0
			40	1000	CYS	0
		TOTAL:				0
31908	HAST	130C, 85%R.H.,5.5V	77	96	HRS	
		TOTAL:				
31909	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	0

PROJECT NO: 27781

RELIABILITY MONITOR

DS1233Z-010 JUL '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1233	A5-500	0326	DU338107AKA	3	SOT223	140x1.7	Hana
PROCESS 1P, 1M, 1.2um, ZTC P1, Ndepletion ,L Passivation w/Nitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse: °C
 Vuse: Volts

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31913	HIGH TEMP OP LIFE	125C, 5.5 VOLTS	80	500	HRS	0
		125C, 5.5 VOLTS	80	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 12	DEVICE HRS: 7.55E+07
31910	ULTRASOUND	J-STD-020	4	1	DYS	0
		TOTAL:				0
31911	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	241	24	HRS	
		85 C/85% R.H.	241	168	HRS	
		235C	241	3	PASS	0
		TOTAL:				0
31912	PRECONDITION U/S	J-STD-020	4	2	DYS	0
		TOTAL:				0
31914	TEMP CYCLE	-55C TO 125C	40	700	CYS	0
			40	1000	CYS	0
		TOTAL:				0
31915	HAST	130C, 85%R.H.,5.5V	77	96	HRS	0
		TOTAL:				0
31916	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	0

PROJECT NO: 26501

RELIABILITY MONITOR

DS1267-010 APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1267	A1-50	0309	DK236020AFA	20	TSSOP	4.4x0.9	ATP (Amkor, PI)
PROCESS	1P, 1M, 1.2um, II Poly1, TEOS Passivation w/Nov TEOS Oxide-Nitride						

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse: °C
 Vuse: Volts

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31316	HIGH TEMP OP LIFE	125C, 5.5 V, -4.0V	80	500	HRS	0
		125C, 5.5 V, -4.0V	80	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 12	DEVICE HRS: 7.55E+07
31313	ULTRASOUND	J-STD-020	4	5	DYS	0
		TOTAL:				0
31314	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	241	24	HRS	
		85 C/85% R.H.	241	168	HRS	
		235C	241	3	PASS	0
		TOTAL:				0
31315	PRECONDITION U/S	J-STD-020	4	2	DYS	0
		TOTAL:				0
31317	TEMP CYCLE	-55C TO 125C	40	500	CYS	0
			40	1000	CYS	0
		TOTAL:				0
31318	BIASED MOISTURE	85/85, 5.5 VOLTS	77	500	HRS	0
			77	1000	HRS	0
		TOTAL:				0

PROJECT NO: 18887

RELIABILITY MONITOR

DS1267-010 APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1267	A1-50	0309	DK236020AFA	20	TSSOP	4.4x0.9	ATP (Amkor, PI)
PROCESS 1P, 1M, 1.2um, II Poly1, TEOS Passivation w/Nov TEOS Oxide-Nitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf: <input type="text" value="60%"/>	Tuse: <input type="text" value="25 °C"/>
Ea: <input type="text" value="0.7"/>	Vuse: <input type="text" value="5.5 Volts"/>
β: <input type="text" value="0"/>	

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31319	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	0
TOTAL:						0

PROJECT NO: 18887

RELIABILITY MONITOR

DS1267-010 OCT '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1267	A1-50	0340	DK230310ACA	20	TSSOP	4.4x0.9	ATP (Amkor, PI)
PROCESS	1P, 1M, 1.2um, II Poly1, TEOS Passivation w/Nov TEOS Oxide-Nitride						

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf: <input type="text" value="60%"/>	Tuse: <input type="text" value="25 °C"/>
Ea: <input type="text" value="0.7"/>	Vuse: <input type="text" value="5.5 Volts"/>
β: <input type="text" value="0"/>	

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
32762	HIGH VOLTAGE LIFE	125C, 6.0 V, -4.0V	80	500	HRS	0
		TOTAL:	24	FAIL RATE (Fits):	DEVICE HRS: 3.77E+07	0
32759	ULTRASOUND	J-STD-020	4	5	DYS	0
		TOTAL:				0
32760	STORAGE LIFE	125C	241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.	241	168	HRS	
	CONVECTION REFLOW	235C	241	3	PASS	0
		TOTAL:				0
32761	PRECONDITION U/S	J-STD-020	4	2	DYS	0
		TOTAL:				0
32763	TEMP CYCLE	-55C TO 125C	40	500	CYS	0
			40	1000	CYS	0
		TOTAL:				0
32764	BIASED MOISTURE	85/85, 5.5 VOLTS	77	500	HRS	0
		TOTAL:				0
32765	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	0
		TOTAL:				0

PROJECT NO: 29487

RELIABILITY MONITOR

DS1620 OCT '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1620	D1	0334	DU110113AAD	8	SOIC	208x1.9	Hana
PROCESS		D8W-1P1M,HPVt,E2		LOCOS:GOI		Passivation w/Nov TEOS Oxide-Nitride	

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse: °C
 Vuse: Volts

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
32504	HIGH TEMP OP LIFE	125C, 5.5 VOLTS	80	500	HRS	0
		125C, 5.5 VOLTS	80	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 12	DEVICE HRS: 7.55E+07
32501	ULTRASOUND	J-STD-020	4	7	DYS	0
		TOTAL:				0
32502	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	244	24	HRS	
		85 C/85% R.H.	244	168	HRS	
		235C	244	3	PASS	0
		TOTAL:				0
32503	PRECONDITION U/S	J-STD-020	4	7	DYS	0
		TOTAL:				0
32505	TEMP CYCLE	-55C TO 125C	40	500	CYS	0
			40	1000	CYS	0
		TOTAL:				0
32506	BIASED MOISTURE	85/85, 5.5 VOLTS	70	500	HRS	0
		TOTAL:				0
32507	WRITE CYCLE STRESS	85 C, 5.5 VOLTS	50	50	KCYS	0

PROJECT NO: 28948

RELIABILITY MONITOR

DS1620 OCT '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1620	D1	0334	DU110113AAD	8	SOIC	208x1.9	Hana
PROCESS		D8W-1P1M,HPVt,E2 LOCOS:GOI		Passivation w/Nov TEOS Oxide-Nitride			

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse: °C
 Vuse: Volts

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
		TOTAL:				0
32508	STORAGE LIFE	150C	50	500	HRS	0
		TOTAL:				0

PROJECT NO: 28948

RELIABILITY MONITOR

DS1621 JUN '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1621	A7	0247	DK104614AAB	8	SOIC	150x1.4	ATP (Amkor, PI)
PROCESS		D8W-1P1M,HPVt,E2		LOCOS:GOI		Passivation w/Nov TEOS Oxide-Nitride	

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse: °C
 Vuse: Volts

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31729	HIGH TEMP OP LIFE	125C, 5.5 VOLTS	77	500	HRS	0
		125C, 5.5 VOLTS	77	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 13	DEVICE HRS: 7.26E+07
31726	ULTRASOUND	J-STD-020	4	7	DYS	0
		TOTAL:				0
31727	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	241	24	HRS	
		85 C/85% R.H.	241	168	HRS	
		235C	241	3	PASS	0
		TOTAL:				0
31728	PRECONDITION U/S	J-STD-020	4	7	DYS	0
		TOTAL:				0
31730	TEMP CYCLE	-55C TO 125C	40	500	CYS	0
			40	1000	CYS	0
		TOTAL:				0
31731	BIASED MOISTURE	85/85, 5.5 VOLTS	70	500	HRS	0
			70	1000	HRS	0
		TOTAL:				0

PROJECT NO: 27259

RELIABILITY MONITOR

DS1621 JUN '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1621	A7	0247	DK104614AAB	8	SOIC	150x1.4	ATP (Amkor, PI)
PROCESS		D8W-1P1M,HPVt,E2 LOCOS:GOI		Passivation w/Nov TEOS Oxide-Nitride			

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse: °C
 Vuse: Volts

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31732	WRITE CYCLE STRESS	85 C, 5.5 VOLTS	50	50	KCYS	0
TOTAL:						0
31733	STORAGE LIFE	150C	50	500	HRS	0
TOTAL:						0

PROJECT NO: 27259

RELIABILITY MONITOR

DS1803-010 OCT '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1803	A2-A	0234	DK236047AAB	16	SOIC	150x1.4	ATP (Amkor, PI)
PROCESS 1P, 2M, 0.8um, PdplDiode, WJ Passivation w/Nov TEOS Oxide-Nitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse: °C
 Vuse: Volts

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30229	HIGH VOLTAGE LIFE	125C, 7.0 VOLTS	80	500	HRS	0
		125C, 7.0 VOLTS	80	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 12	DEVICE HRS: 7.55E+07
30226	ULTRASOUND	J-STD-020	4	2	DYS	0
		TOTAL:				0
30227	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	241	24	HRS	
		85 C/85% R.H.	241	168	HRS	
		235C	241	3	PASS	0
		TOTAL:				0
30228	PRECONDITION U/S	J-STD-020	4	2	DYS	0
		TOTAL:				0
30230	TEMP CYCLE	-55C TO 125C	40	500	CYS	0
			40	1000	CYS	0
		TOTAL:				0
30231	BIASED MOISTURE	85/85, 5.5 VOLTS	77	500	HRS	0
			77	1000	HRS	0
		TOTAL:				0

PROJECT NO: 24620

RELIABILITY MONITOR

DS1803-010 OCT '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1803	A2-A	0234	DK236047AAB	16	SOIC	150x1.4	ATP (Amkor, PI)
PROCESS 1P, 2M, 0.8um, PdplDiode, WJ Passivation w/Nov TEOS Oxide-Nitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	<input type="text" value="60%"/>	Tuse:	<input type="text" value="25 °C"/>
Ea:	<input type="text" value="0.7"/>	Vuse:	<input type="text" value="5.5 Volts"/>
β:	<input type="text" value="0"/>		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30232	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	0
TOTAL:						0

RELIABILITY MONITOR

DS1803-010 APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1803	A2-A	0304	DE322628AAB	16	SOIC	150x1.4	OSEP
PROCESS 1P, 2M, 0.8um, PdplDiode, WJ Passivation w/Nov TEOS Oxide-Nitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:	<input type="text" value="60%"/>	Tuse:	<input type="text" value="25 °C"/>
Ea:	<input type="text" value="0.7"/>	Vuse:	<input type="text" value="5.5 Volts"/>
β:	<input type="text" value="0"/>		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31261	HIGH TEMP OP LIFE	125C, 5.25 VOLTS	80	500	HRS	0
		125C, 5.25 VOLTS	80	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 12	DEVICE HRS: 7.55E+07
31258	ULTRASOUND	J-STD-020	4	2	DYS	0
		TOTAL:				0
31259	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	241	24	HRS	
		85 C/85% R.H.	241	168	HRS	
		235C	241	3	PASS	0
		TOTAL:				0
31260	PRECONDITION U/S	J-STD-020	4	2	DYS	0
		TOTAL:				0
31262	TEMP CYCLE	-55C TO 125C	40	500	CYS	0
			40	1000	CYS	0
		TOTAL:				0
31263	BIASED MOISTURE	85/85, 5.5 VOLTS	77	500	HRS	0
			77	1000	HRS	0
		TOTAL:				0

PROJECT NO: 26480

RELIABILITY MONITOR

DS1803-010 APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1803	A2-A	0304	DE322628AAB	16	SOIC	150x1.4	OSEP
PROCESS 1P, 2M, 0.8um, PdplDiode, WJ Passivation w/Nov TEOS Oxide-Nitride							

Summary Data with Chi-Square Distribution Assumed.

Cf:

Tuse:

Stress Ambient Temperature and Voltage to

Ea:

Vuse:

Field Ambient Temperature And Voltage

β:

NO OF

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31264	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	0
TOTAL:						0

PROJECT NO: 26480

RELIABILITY MONITOR

DS2118M JUN '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS2118M	C1-6"	0303	DM316629ABA	36	SSOP	7.5x2.4	Carsem
PROCESS D6S-1P1M,HPVt,N+ESD,TCN3 ALOCO Laser/Nit - Pass/Nit - General LaserPrb							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse:
 Vuse:

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31737	HIGH TEMP OP LIFE	125C, 5.5 VOLTS	80	500	HRS	0
		125C, 5.5 VOLTS	80	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 12	DEVICE HRS: 7.55E+07
31734	ULTRASOUND	J-STD-020	4	6	DYS	0
		TOTAL:				0
31735	STORAGE LIFE	125C	238	48	HRS	
	MOISTURE SOAK	85 C/85% R.H.	238	168	HRS	
	CONVECTION REFLOW	235C	238	3	PASS	0
	TOTAL:					0
31736	PRECONDITION U/S	J-STD-020	4	6	DYS	0
		TOTAL:				0
31738	TEMP CYCLE	-55C TO 125C	77	500	CYS	0
			77	1000	CYS	0
		TOTAL:				0
31739	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	77	168	HRS	0
		TOTAL:				0

PROJECT NO: 27359

RELIABILITY MONITOR

DS2118M SEP '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS2118M	C1-6"	0309	DN319658AAC	36	SSOP	7.5x2.4	ATK (Amkor, K)
PROCESS D6S-1P1M,HPVt,N+ESD,TCN3 ALOCO Laser/Nit - Pass/Nit - General LaserPrb							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse:
 Vuse:

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
32420	HIGH TEMP OP LIFE	125C, 5.5 VOLTS	79	500	HRS	0
		125C, 5.5 VOLTS	79	1000	HRS	
		TOTAL:				FAIL RATE (Fits): 12
32417	ULTRASOUND	J-STD-020	4	6	DYS	0
		TOTAL:				
32419	PRECONDITION U/S	J-STD-020	4	6	DYS	0
		TOTAL:				
32421	TEMP CYCLE	-55C TO 125C	77	500	CYS	0
			77	1000	CYS	0
		TOTAL:				
32422	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	77	168	HRS	0
		TOTAL:				

PROJECT NO: 28420

RELIABILITY MONITOR

DS21352 FEB '03 MONITOR, D.P.

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS21352	A4	0242	DK036653AAA	100	LQFP	14x14x	ATP (Amkor, PI)
PROCESS 2P, 2M, 0.6um, P2Cap, PdD, HP Vts, GO Laser/TEOS Ox - Pass/Nit - Gen.LaserPrb							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse:
 Vuse:

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31029	HIGH TEMP OP LIFE	125C, 3.3 VOLTS	77	500	HRS	0
		125C, 3.3 VOLTS	63	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 14	DEVICE HRS: 6.60E+07
31026	ULTRASOUND	J-STD-020	4	2	DYS	0
		TOTAL:				0
31027	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	241	24	HRS	
		30C/60% R.H.	241	192	HRS	
		235C	241	3	PASS	0
		TOTAL:				0
31028	PRECONDITION U/S	J-STD-020	4	5	DYS	0
		TOTAL:				0
31030	TEMP CYCLE	-55C TO 125C	80	500	CYS	0
			69	1000	CYS	0
		TOTAL:				0
31031	HAST, NO BIAS	130C, 85% R.H.	78	96	HRS	0
		TOTAL:				0

PROJECT NO: 26120

RELIABILITY MONITOR

DS21352 MAY '03 MONITOR, D.P.

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS21352	A4	0312	DC043465AAA	100	LQFP	14x14x	Stats
PROCESS 2P, 2M, 0.6um, P2Cap, PdD, HP Vts, GO Laser/TEOS Ox - Pass/Nit - Gen.LaserPrb							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse:
 Vuse:

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31401	HIGH TEMP OP LIFE	125C, 3.3 VOLTS	77	500	HRS	0
		125C, 3.3 VOLTS	70	1000	HRS	0
		TOTAL:				FAIL RATE (Fits): 13
31398	ULTRASOUND	J-STD-020	4	2	DYS	0
		TOTAL:				
31399	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	241	24	HRS	
		30C/60% R.H.	241	192	HRS	
		235C	241	3	PASS	0
		TOTAL:				
31400	PRECONDITION U/S	J-STD-020	4	5	DYS	0
		TOTAL:				
31402	TEMP CYCLE	-55C TO 125C	80	500	CYS	0
			73	1000	CYS	0
		TOTAL:				
31403	HAST, NO BIAS	130C, 85% R.H.	77	96	HRS	0
		TOTAL:				

PROJECT NO: 26759

RELIABILITY MONITOR

DS2401 AUG '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS2401	C2	0331	DU342603AB	3	TO92	150	Hana
PROCESS 1P, 1M, 0.6um, Pd, Ti/TiN M1 , WJ Laser/TEOS Ox - Pass/Nit - Gen.LaserPrb							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse:
 Vuse:

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
32237	HIGH TEMP OP LIFE	125C, 6.0 VOLTS	80	500	HRS	0
		125C, 6.0 VOLTS	80	1000	HRS	0
		TOTAL:			FAIL RATE (Fits): 12	DEVICE HRS: 7.55E+07
32238	TEMP CYCLE	-55C TO 125C	45	500	CYS	0
			45	1000	CYS	0
		TOTAL:				
32239	HAST	130C, 85%R.H.,5.5V	77	96	HRS	0
		TOTAL:				
32240	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	45	168	HRS	0
		TOTAL:				

PROJECT NO: 28159

RELIABILITY MONITOR

DS80C320 SEP '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS80C320	C5	0323	DQ338181AAA	40	PDIP	600	ATEC
PROCESS D6RL-1P1M,SILP1,LLVt,N+ESD PBL:G Passivation w/Nov TEOS Oxide-Nitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse:
 Vuse:

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
32413	HIGH TEMP OP LIFE	125C, 5.5 VOLTS	77	500	HRS	0
		125C, 5.5 VOLTS	77	1000	HRS	
		TOTAL:	13	DEVICE HRS: 7.26E+07		0
32414	TEMP CYCLE	-55C TO 125C	45	500	CYS	0
			45	1000	CYS	0
		TOTAL:				0
32415	BIASED MOISTURE	85/85, 5.5 VOLTS	77	500	HRS	0
			77	1000	HRS	0
		TOTAL:				0
32416	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	45	96	HRS	0
		TOTAL:				0

PROJECT NO: 28609

RELIABILITY MONITOR

DS87C520 DEC '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS87C520	A15-I	0232	DK241602AAA	44	PLCC	650x65	ATP (Amkor, PI)
PROCESS 2P, 1M, 0.8um,ThnEP/Si,ThnOx NdPdDS Passivation w/Nov TEOS Oxide-OxyNitride							

Summary Data with Chi-Square Distribution Assumed.
 Stress Ambient Temperature and Voltage to
 Field Ambient Temperature And Voltage

Cf:
 Ea:
 β:

Tuse:
 Vuse:

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30255	HIGH VOLTAGE LIFE	125C, 7.0 VOLTS	75	500	HRS	0
		125C, 7.0 VOLTS	75	1000	HRS	0
		TOTAL:		FAIL RATE (Fits): 13	DEVICE HRS: 7.07E+07	
30252	ULTRASOUND	J-STD-020	4	2	DYS	0
		TOTAL:				0
30253	STORAGE LIFE MOISTURE SOAK CONVECTION REFLOW	125C	239	24	HRS	
		30C/60% R.H.	239	192	HRS	
		220C	239	3	PASS	0
		TOTAL:				0
30254	PRECONDITION U/S	J-STD-020	4	2	DYS	0
		TOTAL:				0
30256	TEMP CYCLE	-55C TO 125C	50	500	CYS	0
			50	1000	CYS	0
		TOTAL:				0
30257	HAST	130C, 85%R.H.,5.5V	59	96	HRS	0
		TOTAL:				0

PROJECT NO: 24681